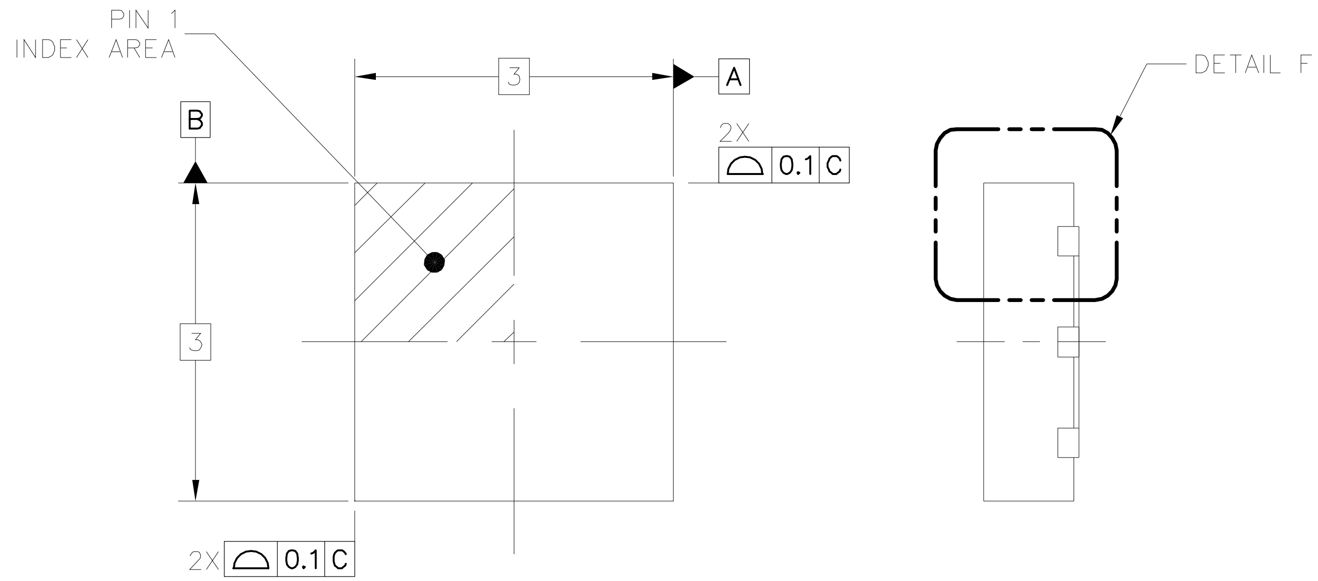

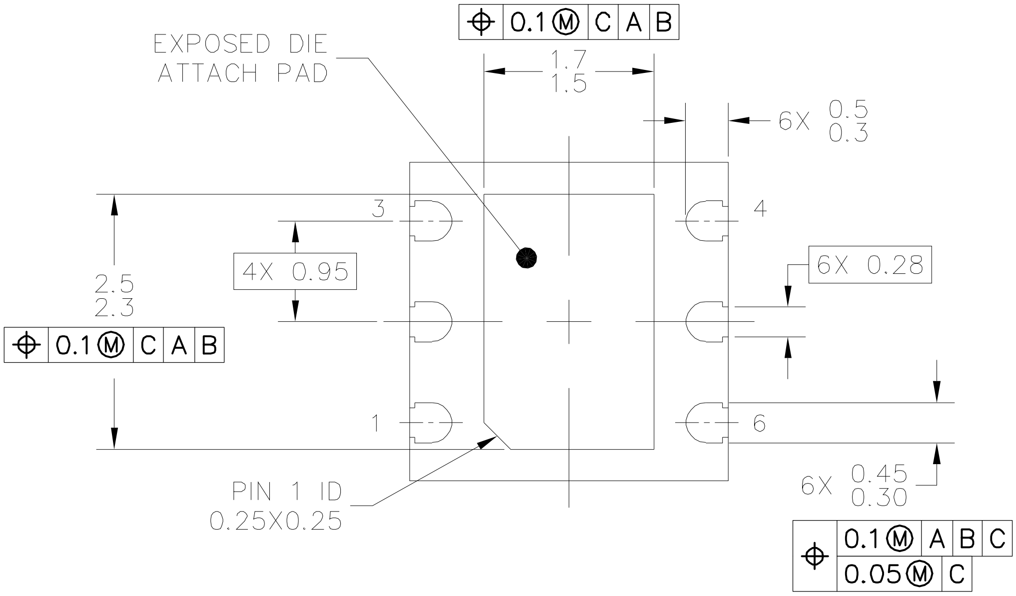

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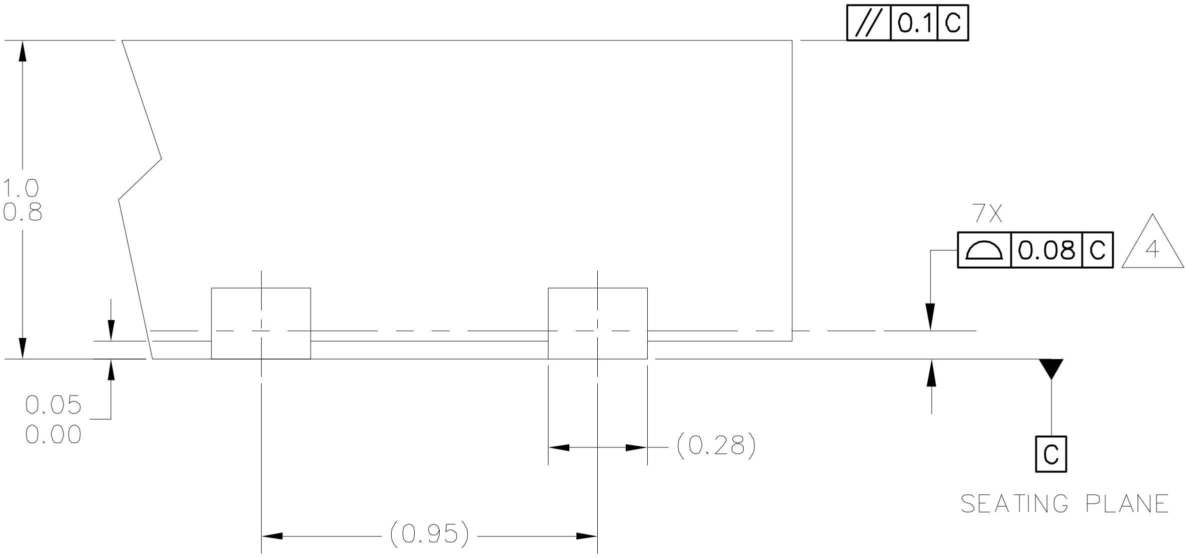
TITLE: QFN, THERMALLY ENHANCED, 3 X 3 X 0.9 PKG, 0.95 PITCH, 6 TERMINAL	DOCUMENT NO: 98ASA00735D	REV: B
	STANDARD: NON-JEDEC	
	SOT907-3	12 JAN 2016



DETAIL F
VIEW ROTATED 90°CW

MECHANICAL OUTLINE	PRINT VERSION NOT TO SCALE
TITLE: QFN, THERMALLY ENHANCED, 3 X 3 X 0.9 PKG, 0.95 PITCH, 6 TERMINAL	DOCUMENT NO: 98ASA00735D REV: B
	STANDARD: NON-JEDEC
	SOT907-3 12 JAN 2016

NOTES:

1. ALL DIMENSIONS ARE IN MILLIMETERS.
2. DIMENSIONING AND TOLERANCING PER ASME Y14.5M−1994.
3. THIS IS A NON−JEDEC REGISTERED PACKAGE.
4. △ COPLANARITY APPLIES TO LEADS AND DIE ATTACH FLAG.
5. MIN. METAL GAP SHOULD BE 0.2 MM.

MECHANICAL OUTLINE

PRINT VERSION NOT TO SCALE

TITLE:
QFN, THERMALLY ENHANCED,
3 X 3 X 0.9 PKG, 0.95 PITCH, 6 TERMINAL

DOCUMENT NO: 98ASA00735D REV: B

STANDARD: NON−JEDEC

SOT907−3 12 JAN 2016